

P/1071-1329

ABSTRACT OF THE DISCLOSURE

An adhesive composition includes a mixture of a ferrite powder and a liquid matrix resin that contains at least one of (A) a polyamic acid and (B) a resin which has an imide bond, is capable of an addition reaction with an amine or capable of self-polymerization, and is capable of dissolving in an organic solvent. The adhesive composition uses a thermally stable polyimide resin and can contain a ferrite powder in a sufficiently high density as to form a satisfactorily closed magnetic circuit structure.

00854767-051404
FOI T50 29245800